559/560 Series
Fuse Blocks for TE5/TR5 Type Fuses

559 Series Holder

560 Series Holder

Additional Information

Resources 559 Series

Accessories 559 Series

Samples 559 Series

Resources 560 Series

Accessories 560 Series

Samples 560 Series

Agency Approvals

Agency	Agency File Number	
	559 Series	560 Series
	N/A	40041024
	N/A	E14721

Product Characteristics

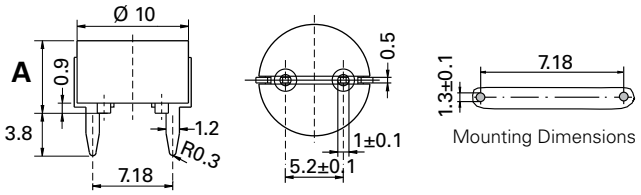
	559 Series (Lead Free)	560 Series
Compatible Fuses	**TR5/TE5**	**TR5/TE5**
Materials	**Holder:** Black Thermoplastic, UL94 V-0	**Holder:** Thermoplastic, UL 94 V-0
	Metal Parts: Copper alloy; solderable tinned	
Electrical Data (23°C)	**Rated Voltage:** 250V	
	Max. Current/Power: 6.3 A /1.6 W	
Mounting	PC Board, 7.18 mm pin spacing	PC Board, 5.08 mm pin spacing
Solderability	max. 260 °C, 10 s (Wave)	
Minimum Cross Section	Conducting path - 0.1 mm^2	
Unit Weight	0.63 g	0.4 g
Ambient Temperature	-40 °C to +85 °C	

Ordering Information

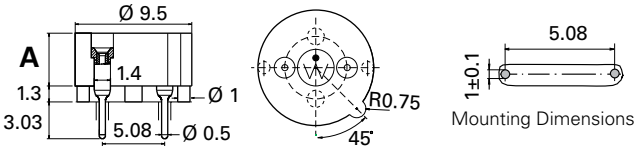
Ordering Number	"A" Height Options	Packaging
55900000001	6.5 mm (code 0001)	1000 Pcs Bulk
55900008011	10 mm (code 8011)	100 Pcs Bulk
56000001319	3.0 mm (code 1319)	500 Pcs Bulk
56000001009	4.3 mm (code 1009)	500 Pcs Bulk
56000001019	4.3 mm (code 1019)	1000 Pcs Bulk

Dimensions (Units in mm)

559 Series



560 Series



Revised: GD. 05/17/21

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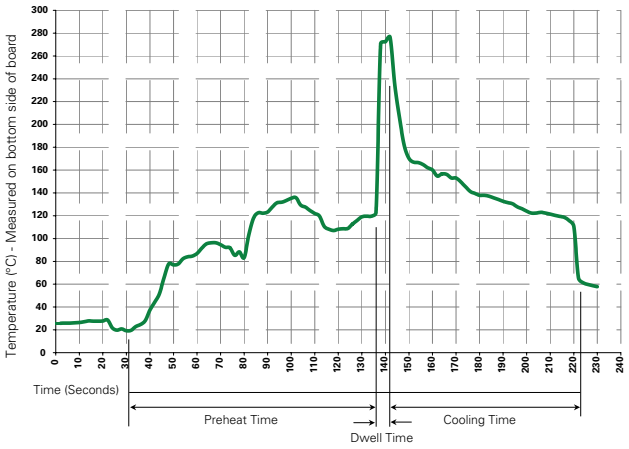
Soldering Parameters - Wave Soldering



Recommended Process Parameters:

Wave Parameter	Lead-Free Recommendation
Preheat: (Depends on Flux Activation Temperature)	(Typical Industry Recommendation)
Temperature Minimum:	100° C
Temperature Maximum:	150° C
Preheat Time:	60-180 seconds
Solder Pot Temperature:	280° C Maximum
Solder Dwell Time:	2-5 seconds

Recommended Hand-Solder Parameters:

Solder Iron Temperature: 350° C +/- 5°C

Heating Time: 5 seconds max.

Note: These devices are not recommended for IR or Convection Reflow process.